



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

RAEDER

Examiner:

Nguyen, D.

Serial No.:

09/383,876

Group Art Unit:

3723

Filed:

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Docket No.:

AMDA.316PA

Title:

POLISHING UNIFORMITY VIA PAD CONDITIONING

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this communication is being deposited in the United States Postal Service, as first class mail, in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on November 30, 2001.

By: Kelly S. Waltigney
Kelly S. Waltigney

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OFFICE ACTION RESPONSE

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated August 31, 2001, please consider the following amendments and response in connection with the above application.

In the Drawings

Please find replacement Figure 2 with required correction to reference character.

In the Specification

Please replace the following paragraphs as follows (attached to this Response find marked-up revision to the Specification):

On pages 7-8, lines 18-22 and 1-6 respectively:

FIG. 1 shows a top view and FIG. 2 shows a side view of a CMP arrangement 100, according to another example embodiment of the present invention. The CMP arrangement includes a polishing table 210 having a polishing pad 140. The polishing table 210 is capable of rotation, such as shown by directional arrow 141. A wafer carrier 130 is arranged over the pad